WHAT IS CLAIMED IS:

1. A sealable adhesive sheet configured to seal an electronic element mounted on a board and adhere to the board comprising:

an adhesive composition, wherein

the adhesive composition contains a thermosetting component, 55 mass% or more and 85 mass% or less of an inorganic filler, and 0.5 mass% or more and 10 mass% or less of a coupling agent, and

a generation amount of an outgas at the time of heating the sealable adhesive sheet at 150°C for 30 minutes with respect to the sealable adhesive sheet before heating is 750 ppm or more.

2. The sealable adhesive sheet according to claim 1, wherein

the mixed amount of the coupling agent with respect to 100 parts by mass of the total amount of the thermosetting component and the inorganic filler is 1 part by mass or more.

3. The sealable adhesive sheet according to claim 1, wherein

the coupling agent is a silane coupling agent containing an epoxy group.

4. The sealable adhesive sheet according to claim 1 further comprising:

a remaining solvent, wherein

a ratio of the remaining solvent in the sealable adhesive sheet is 5 ppm or more.